

SML13RGB2KT-TR

Red/Green/Blue

Surface Mount LED

3.5 × 2.75 × 1.9 mm Chip LED

120° viewing angle

DWG BY:
LL / GP
11-22-11

CHK BY:
PL
11-22-11

REVISION LTR: -
11-22-11

1. SPECIFICATIONS

(1) Absolute Maximum Ratings

(Ta=25°C)

Parameter	Symbol	MAX.	Unit
Continuous Forward Current	If	R 25	mA
		G 25	
		B 25	
Pulse Forward Current*	Ifp	R 100	mA
		G 100	
		B 100	
Power Consumption	Pc	R 65	mW
		G 95	
		B 95	
Electrostatic Discharge	ESD	R 2000	V
		G 1000	
		B 1000	
Operating Temperature Range	Topr	-40 ~ +85	°C
Storage Temperature Range	Tstg	-40 ~ +100	°C
Reverse Voltage	Vr	5	V
Soldering Temperature	Tslid	Reflow Soldering: 260°C /10sec	
		Hand Soldering: 350°C /3sec	

*Duty 1/10 @ 1KHZ

(2) Electrical / Optical Characteristics

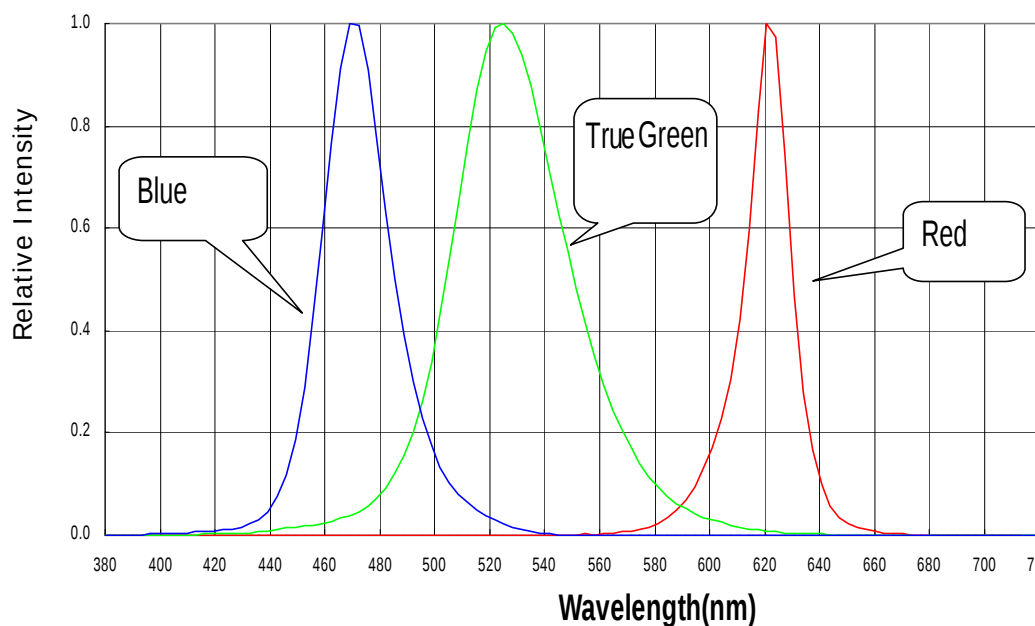
(Ta = 25 °C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Forward Voltage*	Vf	R 1.5	2.2	2.5	V	If=20mA
		G 2.8	3.2	3.8		
		B 2.8	3.1	3.8		
Luminous intensity*	Iv	R 460	670	/	mcd	If=20mA
		G 460	980	/		If=20mA
		B 140	310	/		If=20mA
Dominant Wavelength	λ d	R 615	622	625	nm	If=20mA
		G 520	524	530		
		B 465	469	475		
Spectrum Radiation Bandwidth	Δ λ	R /	22	/	nm	If=20mA
		G /	33	/		
		B /	26	/		
Reverse Current	Ir	R /	/	10	uA	Vr=5V
		G /	/	10		
		B /	/	10		
Viewing Angle*	2θ 1/2	/	120	/	Deg	If=20mA

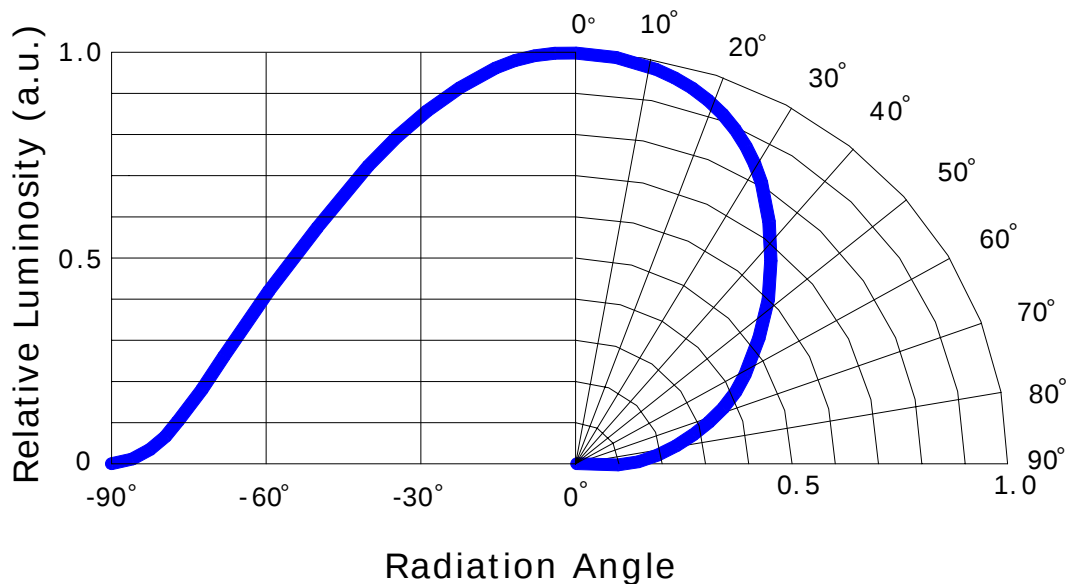
- *Forward voltage measurement allowance is $\pm 0.1V$.
- *Luminous intensity is measured with a light sensor and filter combination that approximates the CIE eye-response curve.
- *Luminous Intensity Measurement Allowance is $\pm 10\%$.
- *Dominant Wavelength measurement allowance is $\pm 1nm$.
- * $2\theta_{1/2}$ is the off-axis angle at which the luminous intensity is half the axial luminous intensity.

Typical Electrical / Optical Characteristics Curves

Wavelength Distribution

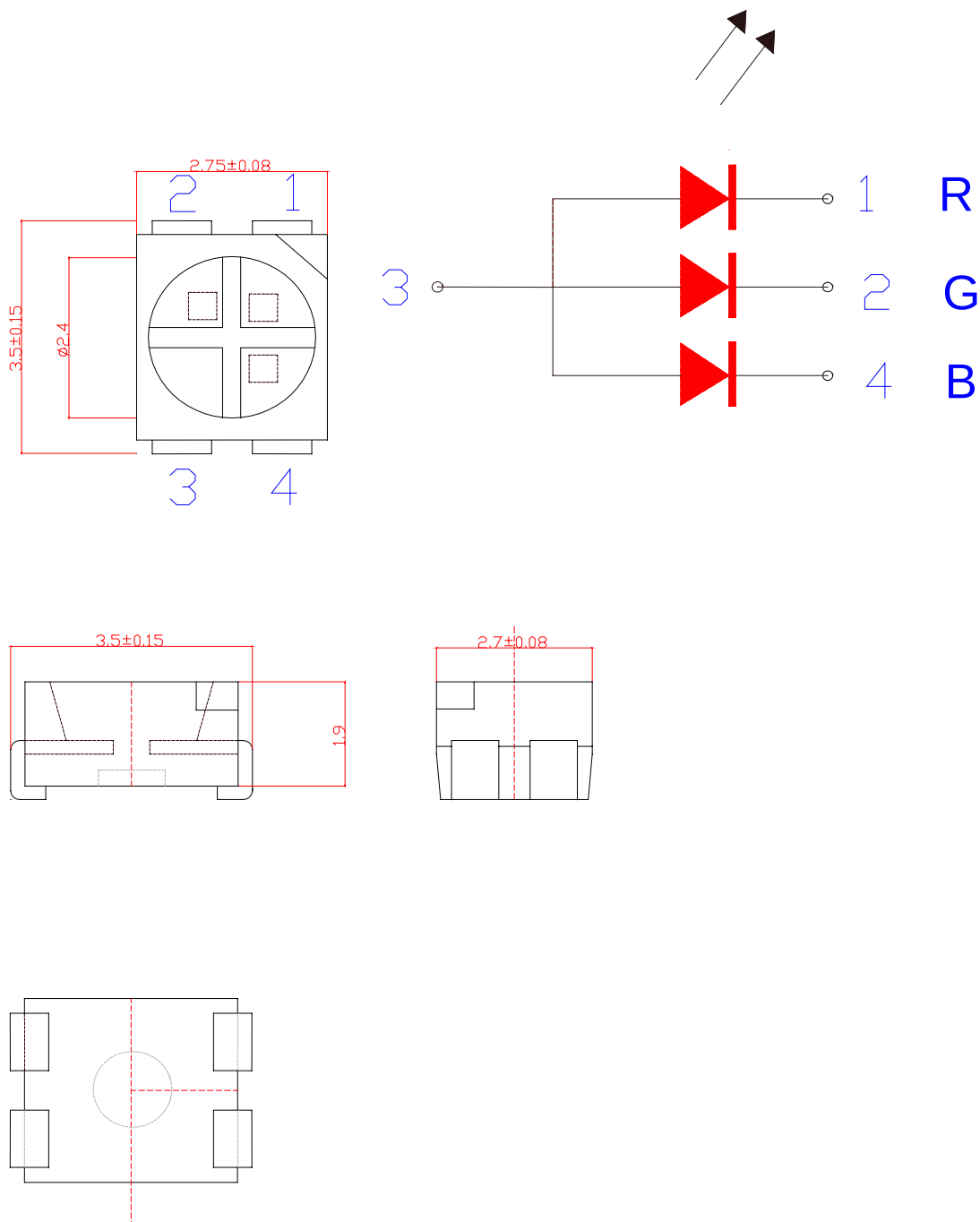


Beam Pattern



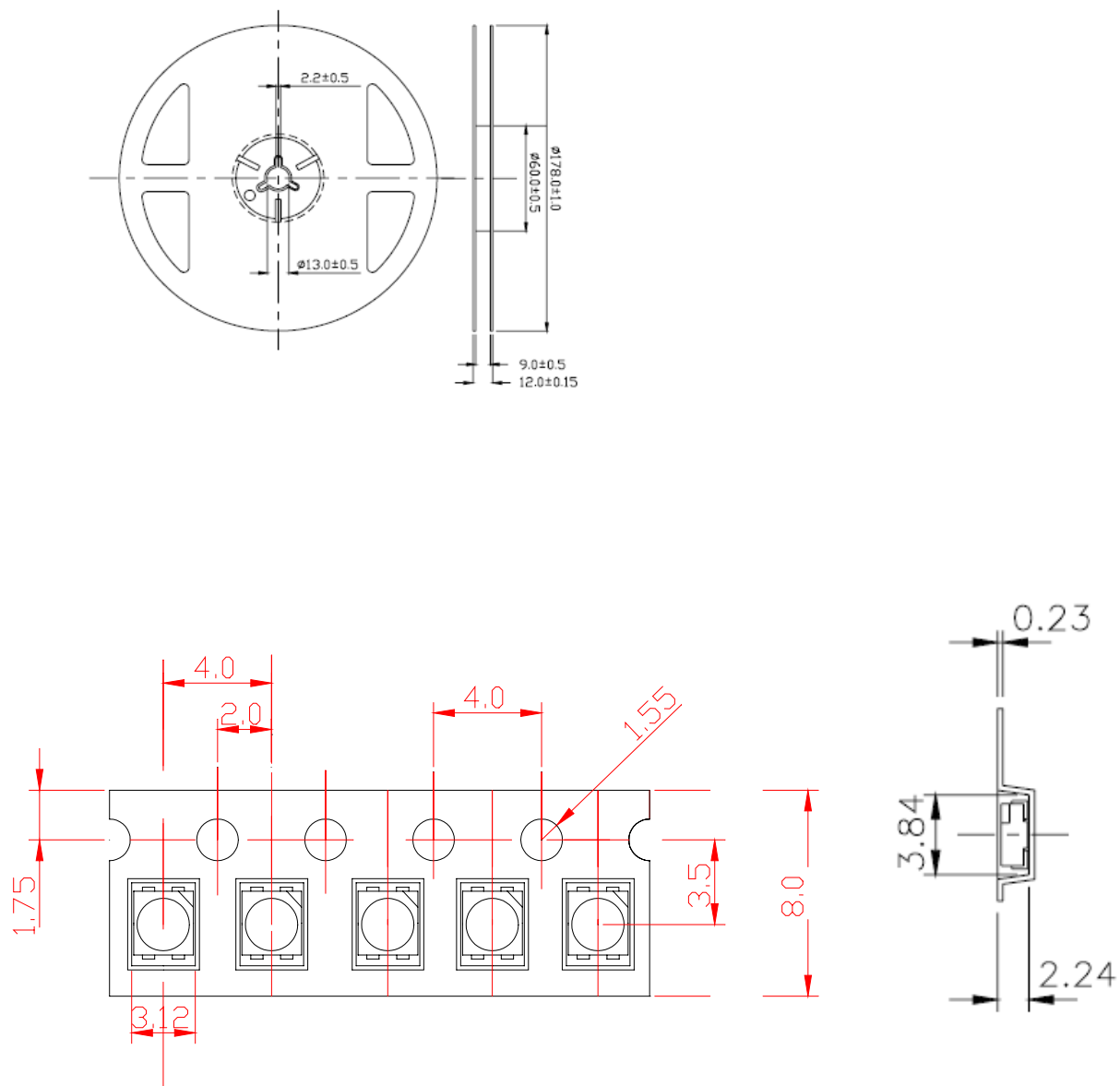
2. Package

Outline Dimension (unit= mm)



1. All dimensions are in millimeters.
2. Tolerances are ± 0.1 mm, unless otherwise noted.

Taping Dimension (unit = mm)



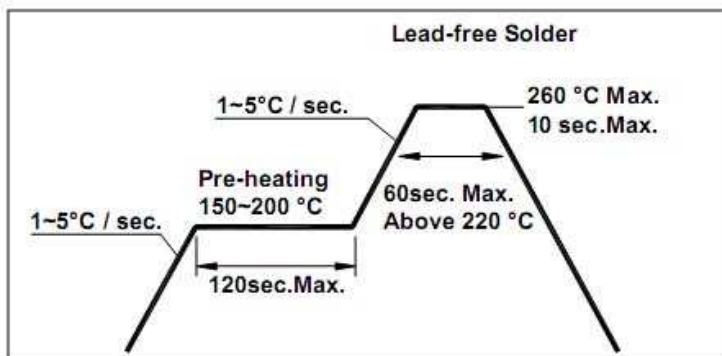
Tolerance: ± 0.2 (unit = mm)

Quantity: 1000 pcs/Reel

3. Handling Precaution

Recommended soldering conditions

1.1 Reflow solder temperature profile



1.2 Soldering conditions

- Reflow soldering should not be done more than twice.
- When soldering, do not stress on LEDs during heating.
- After soldering, do not warp the circuit board.

Repairing

- Repair should not be done after the LEDs have been soldered. When repair is unavoidable, double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will be damaged by repair or not.

Cleaning

- It is recommended to use isopropyl alcohol as a solvent to clean the LEDs. When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the package and the resin or not.

Advice on Device Usage

- It is recommended that user should complete the use of the whole package within 8 hours upon unsealing. In the event of incomplete usage, it is advised that user preheat the remaining devices at 60° for 8 hours prior to use.